US Foils, Inc. CEC1 - FTP Conductive Copper Tape provides excellent performance in grounding and EMI/RFI shielding applications and consists of a 1 ounce, deadsoft, 110 electrolytic tough pitch copper that is 99.9% pure. Backed by a 2 Mil acrylic transfer adhesive which is also electrically conductive, this product is designed for laminating to a variety of surfaces including metal substrates, painted surfaces, and various plastic films. The adhesive features good chemical resistance, moderate tack, and high shear strength.

Additional features include excellent Z direction conductivity, and a 76# moisture resistant polycoated release liner.

Surfaces to which this tape is applied should be clean, dry, dust-free, and have no oily or other residues.

Typical Metal Performance Data:

Copper Thickness

1.4 Mils (.0014")

Copper - Tensile Strength

26-38 Ksi

<table>
<thead>
<tr>
<th>TYPICAL SHIELDING ATTENUATION PERFORMANCE</th>
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<tbody>
<tr>
<td>Frequency</td>
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<tr>
<td>200 KHz Magnetic Field</td>
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<tr>
<td>200 KHz, Electrical Field</td>
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<tr>
<td>1 MHz, Electrical Field</td>
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<tr>
<td>10 MHz, Electrical Field</td>
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<tr>
<td>400 MHz, Plane Wave</td>
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<tr>
<td>10 GHz Plane Wave</td>
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</tbody>
</table>

Flame Retardancy (ASTM E84-04)
Surface Burning Characteristics Pass
Typical Adhesive Performance Data:

Adhesive Thickness
2 Mils

Peel Adhesion (PSTC - 101/180°)
Initial to SS (20 min dwell)
Oz./Inch 47  N/25mm 13.2

Holding Power (PSTC 107 Mod./178°)
2.2 psi (1"x1"x1000g) >600 min.

Resistivity (WIN TM 070)
5m Ω

Minimum Application Temperature
50 Degrees F

No Load Applied, Service Temperature Range
-40 to 250 Degrees F